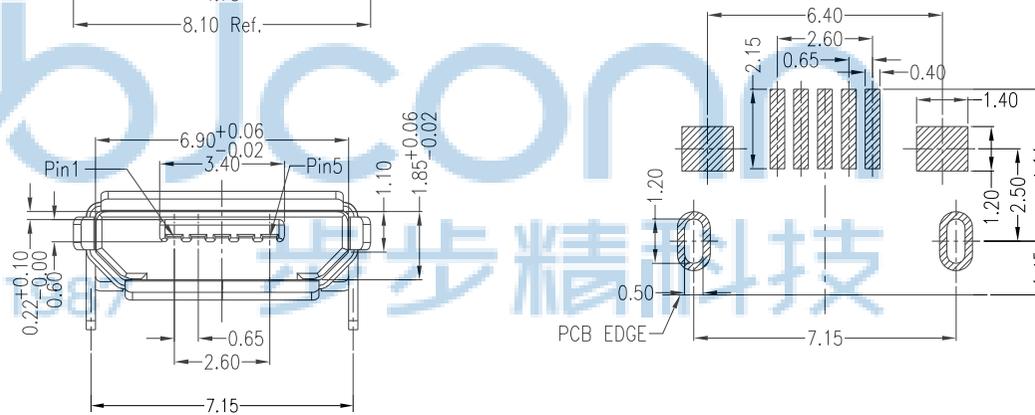
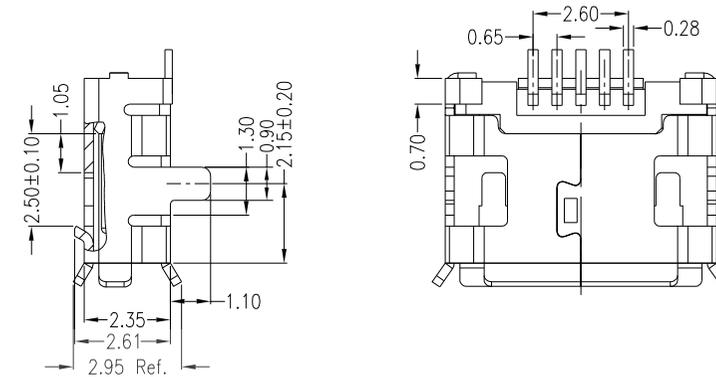
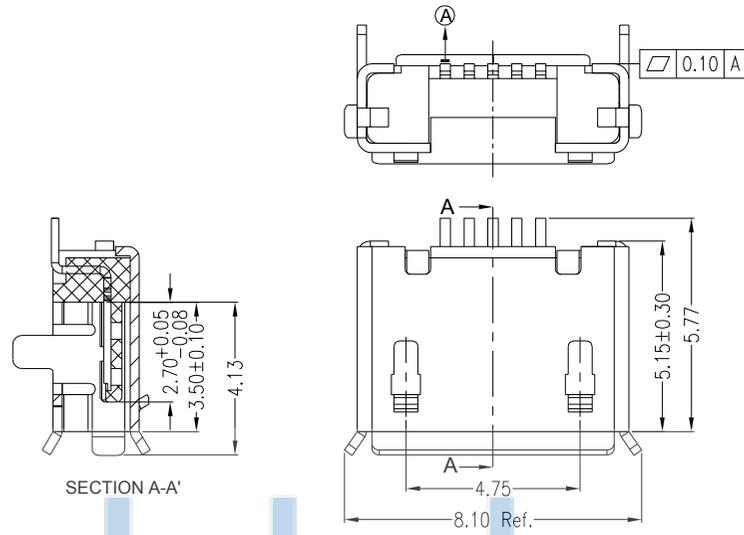


REV.	ECN NO.	CONTENT	DATE	ENGINEER
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Note:

1.Material:

- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.20mm
- 1.3 Shell: copper alloy,t=0.25mm / sus

2.Specification:

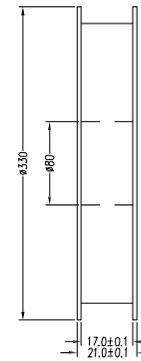
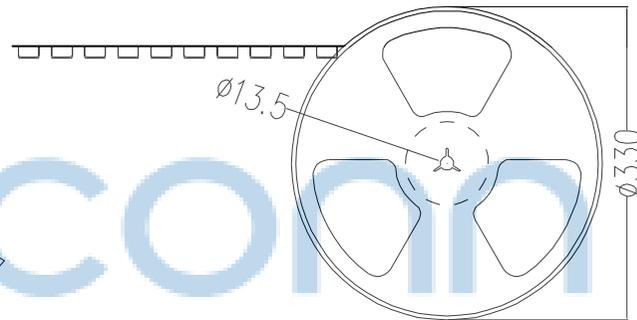
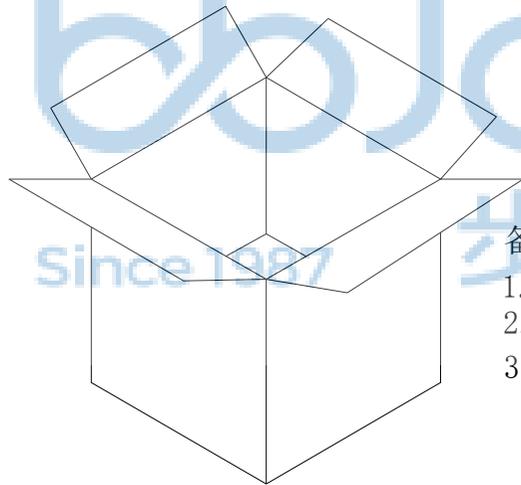
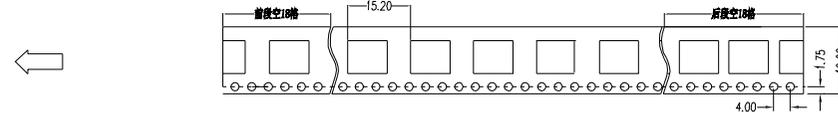
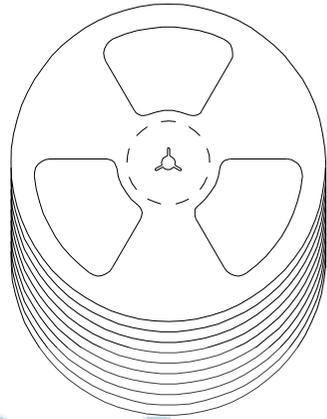
- 2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 30 mΩ Max.
- 2.4 Insulation resistance: 100 MΩ Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.
- 2.7 Temperature range: -30°C~80°C

RECOMMENDED PCB LAYOUT  
PCB图仅供参考



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.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		X': ±3" X'': ±2" X'': ±1"	
APPD.	JM_Zheng	23/05'02	NAME: MICRO-5P 内插无柱 脚距7.2 焊脚加长0.75 脚长1.1 L=5.15 不锈钢壳
CHKD.	LYX	23/05'02	PJ. NO.: MC.01.21-11-1004 SIZE: A4   DRW NO.:
PDWG.NO:	0113-1	DR.	SGF 23/05'02
FINISH: SEE NOTES		MAT'L.: SEE NOTES	
SCALE: N/A		REV.: A3	UNIT: mm   PAGE: 1/1

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0			2023 20/04	



- 1000 / PCS 卷
- 备注:
1. 包装数量: 1000 / PCS / 卷, 10卷 / 箱或15卷 / 箱。
  2. 包装袋长度: 每卷前后各空10-20个空格, 中间包装。
  3. 材质:  
载体: 聚丙烯 (PS), 阻抗 $10^{6-9} \Omega$   
上带: 聚乙烯 (PET), 阻抗 $10^{6-11} \Omega$   
卷盘: 聚苯乙烯。

纸箱规格: 345\*345\*23MM  
纸箱规格: 345\*345\*35MM



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.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		X*: ±3* X*: ±2* XX*: ±1*	
APPD. JM_Zheng 23/05'02		NAME: MICRO-5P 内插无柱 脚距7.2 焊脚加长0.75 脚长1.1 L=5.15 不锈钢壳	
CHKD. LYX 23/05'02		PJ. NO.: MC.01.21-11-1004	
DR. SGF 23/05'02		SIZE: A4 DRW NO.:	
PDWG.NO: 0113-1		FINISH: SEE NOTES MAT'L.: SEE NOTES	
		SCALE: N/A REV.: A3 UNIT: mm PAGE: 1/1	